

# CONDUCTIVE VIA FILL CVF-6030

## DESCRIPTION

Conductive Via Fill CVF-6030 is a two-part filled epoxy system designed to provide electrical and thermal conductivity in PWB and PBGA applications. Applied via stencil, CVF-6030 is an effective, economical fill for vias. When planarized, CVF-6030 is receptive to plating and soldering. Because the via fill exhibits no shrinkage, electrical and thermal conductivity are retained during curing. Vias up to 0.75 mm diameter may be filled with excellent results. The long pot life of CVF-6030 enhances clean-up while its fast cure reduces processing time. Because CVF-6030 is a two-part system, material may be left at room temperature for extended periods, further enhancing processing.

## PROPERTIES

System	Two-Part
Composition	Silver filled epoxy
Viscosity	110,000-140,000 cps
Thinner	CVF-6030 Thinner
Electrical Resistivity, nominal	$3 \times 10^{-4}$ ohm-cm
Thermal Conductivity	> 100 BTU/ft <sup>2</sup> /hr./°F./in.
Outgassing	< 0.01%/100 hours @ 125 °C
Stencil Type	3-4 stainless steel
Aspect Ratio (depth:diameter)	6:1
Clean-up Solvent	<i>Iso</i> -propyl alcohol; acetone
Temperature Stability Range	-65 °C to + 175 °C
Storage	Room Temperature
Shelf Life	1 year @ 25 °C
Pot Life	48 hours @ 25 °C
Mixing Ratio	4 drops (0.124 grams) Part B per 10 grams Part A
Cure Schedule	100 °C for 30 minutes Or 125 °C for 20 minutes Or 150 °C for 15 minutes

## INSTRUCTIONS

CVF-6030 may be applied via stencil to drilled, plated through holes and is then cured as instructed. The stencil heads of the cured via fill may be removed by planarization to yield a smooth, uniform surface. It is then possible to electroplate prior to printing and etching or proceed directly to the print and etch process.

Special Thinner included

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